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REPLACED

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SOLDER BALL CONTACT AND METHOD

ABSTRACT OF THE DISCLOSURE

The invention is a method for attaching an electronic component (40) having Ball Grid Array contacts (36) to a circuit board contact array (31) to prevent the solder balls (36) of the Ball Grid Array from fracturing and distorting during solder reflow when the Ball grid Array contact (36) is attached to a contact (31) on a printed circuit board (30) that has a via (32) extending at least partially through the printed circuit board (30). A solder form (35) is placed over each via (32) in each contact (31) of the contact array. The electronic component (40) that has BGA contacts (36) is placed over the contact array (31) such that each ball (36) of the ball grid array of the electronic component resides on a solder form (35). The component (40) and circuit board (30) is subjected to a solder reflow process to seal the component (40) to the circuit board (30). The solder form (35) at least partially fills the via (32) preventing the BGA contact (36) from collapsing into the via (32).

Figure 2

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